

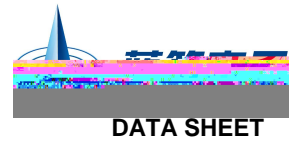


**修订记录 / Revised record**

G	2020-7-28	1			

# BAV99

Rev.G Jul.-2020



## 描述 / Descriptions

SOT-23

Silicon Diode in a SOT-23 Plastic Package.

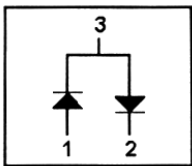
## 特征 / Features

Small signal diode.HF Product.

## 用途 / Applications

High Conductance Ultra Fast Diode.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



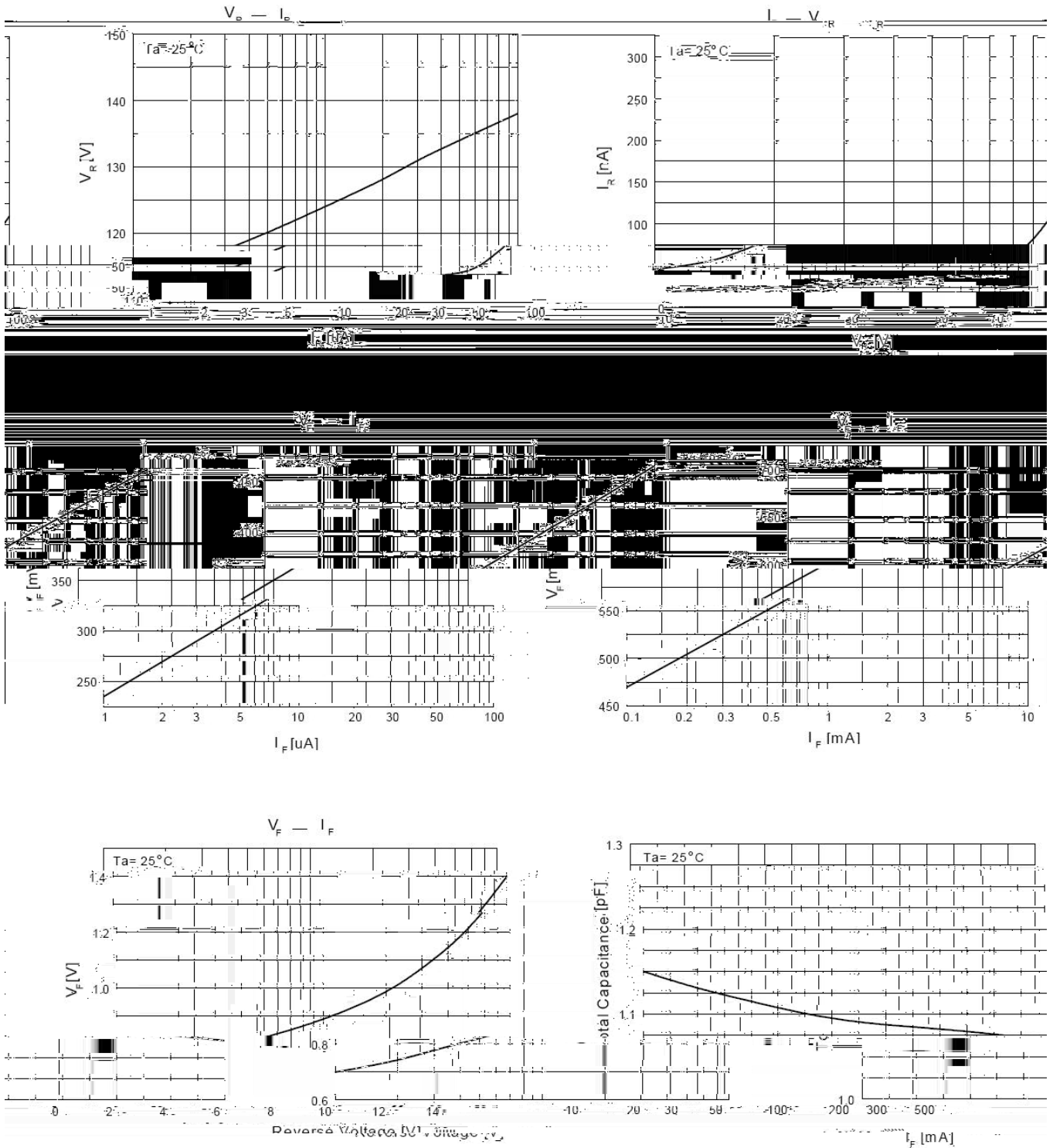
PIN: See Equivalent Circuit.

## 放大及印章代码 / $h_{FE}$ Classifications & Marking

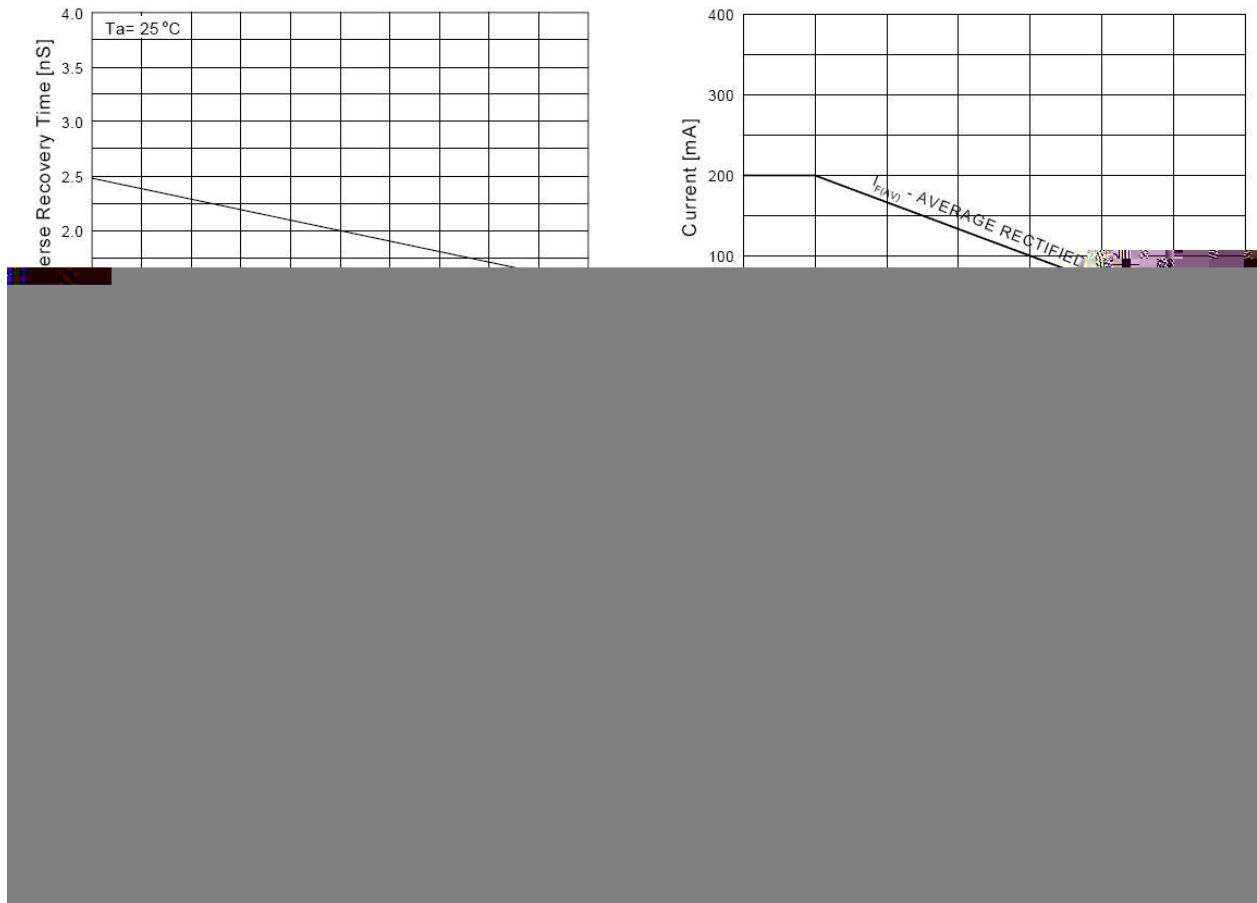
Marking	HA7
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**BAV99**

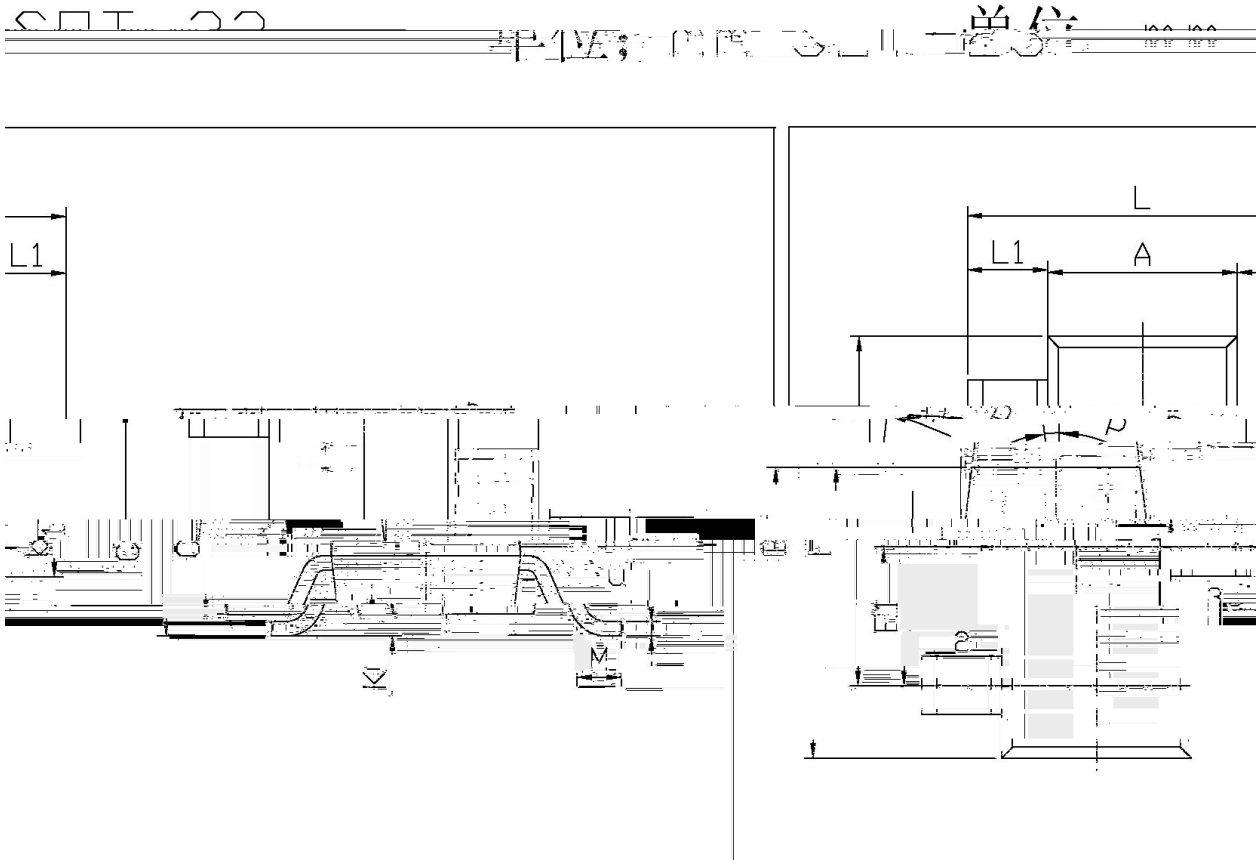
**电参数曲线图 / Electrical Characteristic Curve**



**电参数曲线图 / Electrical Characteristic Curve**

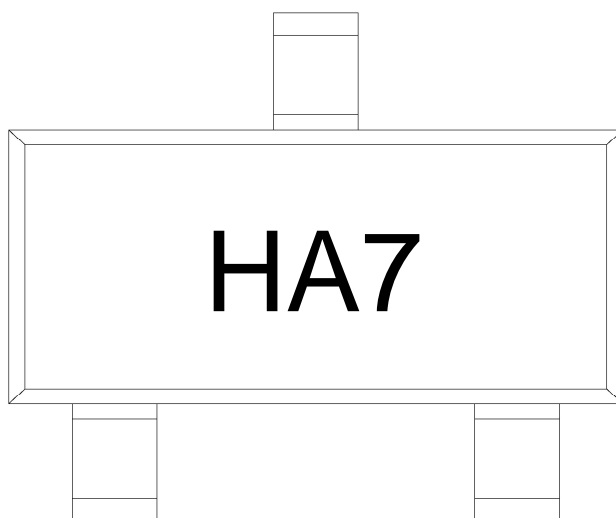


**外形尺寸图 / Package Dimensions**



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10
E	1.70	2.00	P	7°	
E1	0.85	1.05			
b	0.35	0.55			

**印章说明 / Marking Instructions**



H

A7

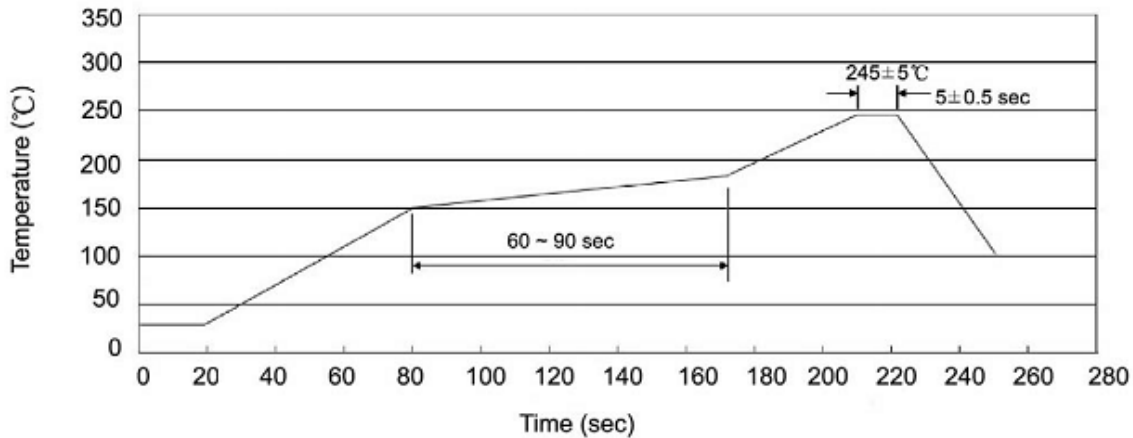
Note:

H: Company Code.

A7: Product Type Code.



**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



Note:

- |   |       |     |       |        |   |
|---|-------|-----|-------|--------|---|
| 1 | 150   | 180 | 60    | 90sec; | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245±5 |     | 5±0.5 | sec;   | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10    | /sec.  | 3. Cooling Speed: 2~10 /sec.            |

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

260±5                      10±1 sec.                      Temp.:260±5℃                      Time:10±1 sec

**包装规格 / Packaging SPEC.**

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

**使用说明 / Notices**